FOR IMMEDIATE RELEASE

Frore Systems Unleashes AirJet®PAK: The 2025 Embedded Award Nominee is the Key to Unlocking AI Performance in Compact Embedded Systems

SAN JOSE, California – February 27, 2025: Frore Systems is transforming the Embedded Systems industry with the introduction of the revolutionary AirJet®PAK, the world's first solid-state active cooling module, which is nominated for the prestigious Embedded Award at the Embedded World Conference in Germany (March 11-13, 2025). The annual Embedded Award honors outstanding innovations in the field of Embedded System technologies. Frore Systems AirJet®PAK is poised to reshape how the world solves the #1 challenge limiting AI performance: HEAT.

The AI Revolution in Embedded Systems Needs AirJet®PAK - Embedded Systems are everywhere. These specialized computers are built to perform dedicated functions and are tucked inside systems we use every day—smart home gadgets, medical devices, cars, smart city and industrial machines. They're compact, efficient, and quietly power our modern lives. Artificial intelligence in Embedded Systems is advancing rapidly, but the heat generated by the superior AI Processors is a critical obstacle to sustained peak performance. The new AirJet®PAK cooling modules are the ultimate solution, removing heat efficiently to ensure Embedded Systems can perform at their peak all the time – with no compromises.

AirJet®PAK is an ultra-compact, plug-and-play cooling module that is dustproof, water-resistant, and completely silent.

Redefining Cooling for AI - Traditional cooling methods, like bulky heat sinks and noisy fans, fall short in demanding environments. Fans pull dust and moisture into devices, causing failures, while heat sinks add enormous size and weight.

AirJet®PAK changes the game:

- Smaller, lighter designs: Systems using AirJet®PAK are significantly smaller and lighter than those relying on traditional passive heatsink based solutions.
- Unmatched durability: With no moving parts that break, AirJet PAK offers long-term reliability that traditional fans just can't match.
- Universal compatibility: Designed for a range of Embedded AI Systems, including NVIDIA Jetson, Qualcomm, NXP, and AMD/Xilinx SoMs, AirJet®PAK unleashes the power of AI in all embedded applications.

For example, the NVIDIA Jetson Orin NX 16GB, capable of up to 100 TOPS, requires efficient cooling to achieve its full potential. AirJet®PAK provides the same performance as traditional passive solutions, but 85% smaller and lighter, revolutionizing system design.

Power and Performance in Every Size - AirJet®PAK modules are available in multiple configurations, tailored to meet the needs of diverse applications:

- AirJet®PAK 5C: Delivers up to 33W heat removal and supports 100 TOPS, measuring just 100x65x9.3mm.
- AirJet®PAK 3C: Delivers up to 24W heat removal and supports 80 TOPS, measuring just 100x65x5.8mm.
- AirJet®PAK 1C: Delivers up to 9W heat removal and supports 28 TOPS, measuring just 30x65x5.8mm.

Scalability is built into the AirJet®PAK system. Multiple modules can be combined to handle higher processing loads and greater heat dissipation, making it the ideal choice for future-proofing AI designs.

Disrupting the Embedded Industry - Frore Systems isn't just solving a problem — it's transforming the embedded systems industry. By unlocking the full potential of AI systems in compact, rugged Embedded Systems, AirJet®PAK is setting a new standard for cooling solutions. Frore Systems is showing the world what's possible when heat is no longer a barrier to progress.

Frore Systems will be at the Embedded World Conference in Germany, March 11-13, 2025, giving everyone the opportunity to see the technology in action, with live demonstrations of numerous Embedded Systems with AirJet®PAK, and showcasing a range of commercial products with AirJet that are already shipping. Frore System's groundbreaking products unlock the performance needed for all Embedded AI Systems.

About Frore Systems

Frore Systems is the developer of breakthrough thermal technology for electronic and consumer devices. The company's active cooling solutions, the AirJet®Mini, AirJet®Mini Slim, AirJet®Mini Sport, and AirJet®PAKs, are integrated into devices to remove heat silently, resulting in major performance gains and enabling thinner, lighter, silent, vibration free, dustproof and waterproof devices. Frore Systems is headquartered in San Jose, CA with an office and manufacturing facility in Taiwan. For more information, please visit https://froresystems.com/

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